What is claimed is:

1. A method for processing a component that includes a substrate and a coating coupled to the substrate, the method comprising:

applying a laser beam to the coating in a first stage, the first stage characterized by a first number of pulses of the laser beam and a first offset corresponding to a focal point of the laser beam coinciding with an exterior surface of the coating; and

applying the laser beam to the coating in a second stage, the second stage characterized by a second number of pulses of the laser beam and a second offset corresponding to the focal point of the laser beam being located within a span of the substrate;

wherein execution of the first stage and the second stage open a first hole through the coating, and the first hole is coaxial with a first hole in the substrate.

2. The method of claim 1, wherein the second offset corresponds to the focal point of the laser beam being located below the exterior surface by a threshold amount relative to a total thickness of the coating and the substrate.

3. The method of claim 2, wherein the threshold amount is within a range of 55% to 65% of the total thickness.

4. The method of claim 1, wherein the first number of pulses is different from the second number of pulses.

5. The method of claim 4, wherein the second number of pulses is less than the first number of pulses.

6. The method of claim 1, wherein the laser beam is applied at a first angle relative to the exterior surface of the coating during the first stage and a second angle relative to the exterior surface of the coating during the second stage.

7. The method of claim 6, wherein the first angle is the same as the second angle.

8. The method of claim 1, further comprising:

subsequent to opening the first hole through the coating, translating the component; and

subsequent to translating the component, opening a second hole through the coating, the second hole coaxial with a second hole in the substrate.